

SMPS MOSFET **IRF3703PbF**

HEXFET® Power MOSFET

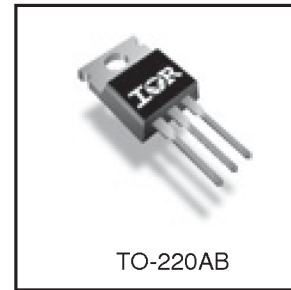
**Applications**

- Synchronous Rectification
- Active ORing
- Lead-Free

$V_{DSS}$	$R_{DS(on) \max}$	$I_D$
30V	2.8m $\Omega$	210A <sup>⑥</sup>

**Benefits**

- Ultra Low On-Resistance
- Low Gate Impedance to Reduce Switching Losses
- Fully Avalanche Rated



**Absolute Maximum Ratings**

	Parameter	Max.	Units
$I_D @ T_C = 25^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10\text{V}$	210 <sup>⑥</sup>	A
$I_D @ T_C = 100^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10\text{V}$	100 <sup>⑥</sup>	
$I_{DM}$	Pulsed Drain Current <sup>①</sup>	1000	
$P_D @ T_C = 25^\circ\text{C}$	Power Dissipation	230	W
$P_D @ T_A = 25^\circ\text{C}$	Power Dissipation	3.8	
	Linear Derating Factor	1.5	W/ $^\circ\text{C}$
$V_{GS}$	Gate-to-Source Voltage	$\pm 20$	V
dv/dt	Peak Diode Recovery dv/dt <sup>③</sup>	5.0	V/ns
$T_J, T_{STG}$	Junction and Storage Temperature Range	-55 to + 175	$^\circ\text{C}$

**Thermal Resistance**

	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case	—	0.65	$^\circ\text{C}/\text{W}$
$R_{\theta CS}$	Case-to-Sink, Flat, Greased Surface	0.5	—	
$R_{\theta JA}$	Junction-to-Ambient	—	62	

Notes <sup>①</sup> through <sup>⑥</sup> are on page 8

# IRF3703PbF

International  
**IR** Rectifier

## Static @ T<sub>J</sub> = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
V <sub>(BR)DSS</sub>	Drain-to-Source Breakdown Voltage	30	—	—	V	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA
ΔV <sub>(BR)DSS</sub> /ΔT <sub>J</sub>	Breakdown Voltage Temp. Coefficient	—	0.028	—	V/°C	Reference to 25°C, I <sub>D</sub> = 1mA
R <sub>DSON</sub>	Static Drain-to-Source On-Resistance	—	2.3	2.8	mΩ	V <sub>GS</sub> = 10V, I <sub>D</sub> = 76A ④
		—	2.8	3.9		V <sub>GS</sub> = 7.0V, I <sub>D</sub> = 76A ④
V <sub>GS(th)</sub>	Gate Threshold Voltage	2.0	—	4.0	V	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA
I <sub>DSS</sub>	Drain-to-Source Leakage Current	—	—	20	μA	V <sub>DS</sub> = 24V, V <sub>GS</sub> = 0V
		—	—	250		V <sub>DS</sub> = 24V, V <sub>GS</sub> = 0V, T <sub>J</sub> = 150°C
I <sub>GSS</sub>	Gate-to-Source Forward Leakage	—	—	200	nA	V <sub>GS</sub> = 20V
	Gate-to-Source Reverse Leakage	—	—	-200		V <sub>GS</sub> = -20V

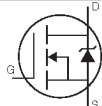
## Dynamic @ T<sub>J</sub> = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
g <sub>fs</sub>	Forward Transconductance	150	—	—	S	V <sub>DS</sub> = 24V, I <sub>D</sub> = 76A
Q <sub>g</sub>	Total Gate Charge	—	209	—	nC	I <sub>D</sub> = 76A
Q <sub>gs</sub>	Gate-to-Source Charge	—	62	—		V <sub>DS</sub> = 24V
Q <sub>gd</sub>	Gate-to-Drain ("Miller") Charge	—	42	—		V <sub>GS</sub> = 10V, ④
t <sub>d(on)</sub>	Turn-On Delay Time	—	18	—	ns	V <sub>DD</sub> = 15V, V <sub>GS</sub> = 10V
t <sub>r</sub>	Rise Time	—	123	—		I <sub>D</sub> = 76A
t <sub>d(off)</sub>	Turn-Off Delay Time	—	53	—		R <sub>G</sub> = 1.8Ω
t <sub>f</sub>	Fall Time	—	24	—		V <sub>GS</sub> = 10V ④
C <sub>iss</sub>	Input Capacitance	—	8250	—	pF	V <sub>GS</sub> = 0V
C <sub>oss</sub>	Output Capacitance	—	3000	—		V <sub>DS</sub> = 25V
C <sub>rss</sub>	Reverse Transfer Capacitance	—	290	—		f = 1.0MHz
C <sub>oss</sub>	Output Capacitance	—	10360	—		V <sub>GS</sub> = 0V, V <sub>DS</sub> = 1.0V, f = 1.0MHz
C <sub>oss</sub>	Output Capacitance	—	3060	—		V <sub>GS</sub> = 0V, V <sub>DS</sub> = 24V, f = 1.0MHz
C <sub>oss eff.</sub>	Effective Output Capacitance	—	2590	—		V <sub>GS</sub> = 0V, V <sub>DS</sub> = 0V to 24V ⑤

## Avalanche Characteristics

	Parameter	Typ.	Max.	Units
E <sub>AS</sub>	Single Pulse Avalanche Energy②	—	1700	mJ
I <sub>AR</sub>	Avalanche Current③	—	76	A
E <sub>AR</sub>	Repetitive Avalanche Energy④	—	23	mJ

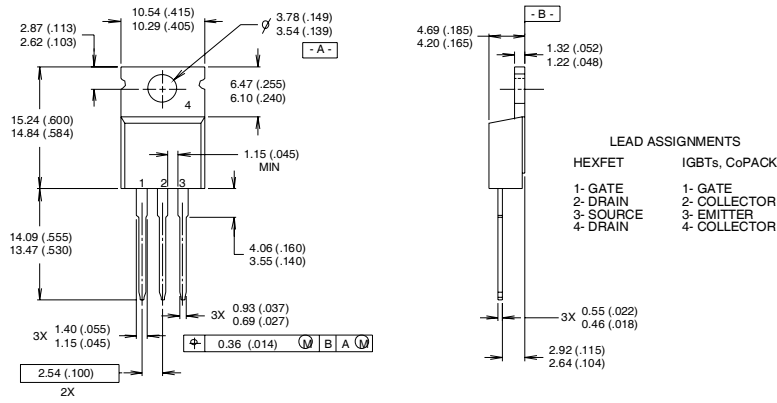
## Diode Characteristics

	Parameter	Min.	Typ.	Max.	Units	Conditions
I <sub>S</sub>	Continuous Source Current (Body Diode)	—	—	210⑥	A	MOSFET symbol showing the integral reverse p-n junction diode. 
I <sub>SM</sub>	Pulsed Source Current (Body Diode) ①	—	—	1000		
V <sub>SD</sub>	Diode Forward Voltage	—	0.8	1.3	V	T <sub>J</sub> = 25°C, I <sub>S</sub> = 76A, V <sub>GS</sub> = 0V ④
t <sub>rr</sub>	Reverse Recovery Time	—	80	120	ns	T <sub>J</sub> = 25°C, I <sub>F</sub> = 76A, V <sub>DS</sub> = 16V
Q <sub>rr</sub>	Reverse Recovery Charge	—	185	275	nC	di/dt = 100A/μs ④

# IRF3703PbF



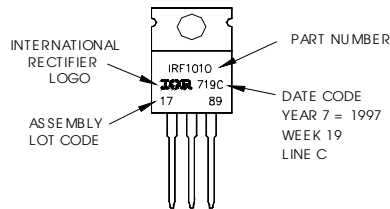
## TO-220AB Package Outline



- NOTES:
- 1 DIMENSIONING & TOLERANCING PER ANSI Y14.5M, 1982.
  - 2 CONTROLLING DIMENSION : INCH
  - 3 OUTLINE CONFORMS TO JEDEC OUTLINE TO-220AB.
  - 4 HEATSINK & LEAD MEASUREMENTS DO NOT INCLUDE BURRS.

## TO-220AB Part Marking Information

EXAMPLE: THIS IS AN IRF1010  
 LOT CODE 1789  
 ASSEMBLED ON WW 19, 1997  
 IN THE ASSEMBLY LINE "C"  
**Note:** "P" in assembly line  
 position indicates "Lead-Free"



### Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature.
- ② Starting  $T_J = 25^\circ\text{C}$ ,  $L = 0.6\text{mH}$   
 $R_G = 25\Omega$ ,  $I_{AS} = 76\text{A}$ .
- ③  $I_{SD} \leq 76\text{A}$ ,  $di/dt \leq 100\text{A}/\mu\text{s}$ ,  $V_{DD} \leq V_{(BR)DSS}$ ,  
 $T_J \leq 175^\circ\text{C}$
- ④ Pulse width  $\leq 300\mu\text{s}$ ; duty cycle  $\leq 2\%$ .
- ⑤  $C_{oss}$  eff. is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 to 80%  $V_{DSS}$
- ⑥ Calculated continuous current based on maximum allowable junction temperature. Package limitation current is 75A

Data and specifications subject to change without notice.  
 This product has been designed and qualified for the industrial market.  
 Qualification Standards can be found on IR's Web site.

